<table>
<thead>
<tr>
<th>Qty</th>
<th>Reference</th>
<th>Value</th>
<th>Description</th>
<th>Size</th>
<th>Part Name</th>
<th>Manufacturer</th>
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<tbody>
<tr>
<td>1</td>
<td>C12</td>
<td>1000pF</td>
<td>Capacitor, Ceramic Chip, 50V, ±10%</td>
<td>603</td>
<td>Std</td>
<td>Std</td>
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<tr>
<td>2</td>
<td>C7 C100</td>
<td>1uF</td>
<td>Capacitor, Ceramic Chip, 16V, ±10%</td>
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<td>Std</td>
<td>Std</td>
</tr>
<tr>
<td>1</td>
<td>C10</td>
<td>open</td>
<td>Capacitor, Ceramic Chip, 25V, ±10%</td>
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<tr>
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<td>C6</td>
<td>0.1uF</td>
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<tr>
<td>2</td>
<td>C5 C8</td>
<td>22uF</td>
<td>Capacitor, Ceramic, 16V, ±20%</td>
<td>1210</td>
<td>C3225X7R1C226M</td>
<td>TDK</td>
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<tr>
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<td>C2</td>
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<td>Capacitor, Ceramic, 10V, ±20%</td>
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<td>C3225X5R1A476M</td>
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<td>1</td>
<td>D1</td>
<td>PDS1040L</td>
<td>Diode, Schottky Barrier, 10A, 40V</td>
<td>Power DI 5</td>
<td>PDS1040L</td>
<td>Diodes Inc.</td>
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<tr>
<td>1</td>
<td>L1</td>
<td>1.5uH</td>
<td>Inductor, 12A, 6.6 milliohms</td>
<td>11.0 x 10.9mm</td>
<td>744323150</td>
<td>Wurth</td>
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<tr>
<td>1</td>
<td>U2</td>
<td>LM3481MM</td>
<td>IC, N-Channel Controller</td>
<td>MSOP</td>
<td>LM3481MM</td>
<td>TI</td>
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<td>1</td>
<td>R102</td>
<td>0</td>
<td>Resistor, Chip, 1/16W, 1%</td>
<td>603</td>
<td>Std</td>
<td>Std</td>
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<tr>
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<td>R101</td>
<td>10</td>
<td>Resistor, Chip, 1/16W, 1%</td>
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<td>Std</td>
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<td>1</td>
<td>R10</td>
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<td>R4-5 R9</td>
<td>200K</td>
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<td>Std</td>
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<tr>
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<td>R3</td>
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<td>Resistor, Chip, 1/16W, 1%</td>
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<td>Std</td>
<td>Std</td>
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<td>R10</td>
<td>324K</td>
<td>Resistor, Chip, 1/16W, 1%</td>
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<td>Std</td>
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<td>R11</td>
<td>42.2K</td>
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<td>R1</td>
<td>0.005</td>
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<td>2010</td>
<td>Std</td>
<td>Std</td>
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<tr>
<td>2</td>
<td>J1-2</td>
<td>ED555/2DS</td>
<td>Terminal Block, 2-pin, 6-A, 3.5mm</td>
<td>0.27” x 0.25”</td>
<td>ED555/2DS</td>
<td>OST</td>
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<tr>
<td>6</td>
<td>TP1-3 TP7-8 TP100</td>
<td>5000</td>
<td>Test Point, Red, Thru Hole Color Keyed</td>
<td>0.1” x 0.1”</td>
<td>Keystone</td>
<td></td>
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<tr>
<td>3</td>
<td>TP4-5 TP101</td>
<td>5001</td>
<td>Test Point, Black, Thru Hole Color Keyed</td>
<td>0.1” x 0.1”</td>
<td>Keystone</td>
<td></td>
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<tr>
<td>1</td>
<td>Q2</td>
<td>CSD16340Q3</td>
<td>MOSFET, N-Ch, 25V, 4.3 milliohm</td>
<td>QFN3.3x3.3 mm</td>
<td>CSD16340Q3</td>
<td>TI</td>
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</tbody>
</table>
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